What is claimed is:

1. An electrical connector, comprising:

a housing;

a plurality of solder masses extending from a surface of the housing for electrically connecting the electrical connector to a circuit substrate; and

a retentive structure extending from the surface of the housing and spaced apart from the plurality of solder masses, the retentive structure comprising a base material and a plating material disposed over at least a portion of the base material;

wherein at least some of the plating material separates from the base material at a reflow temperature of the plurality of solder masses.

2. The electrical connector of claim 1, wherein the reflow temperature is about 180 degrees Celsius.

3. The electrical connector of claim 1, wherein the plating material is selected from the group comprising gold, palladium, platinum, silver, rhodium, iridium, osmium, ruthenium, and rhenium.

4. The electrical connector of claim 1, wherein the plating material comprises gold.

5. The electrical connector of claim 1, wherein the plating material comprises palladium.

6. The electrical connector of claim 1, wherein at least about 40% by volume of the plating material separates from the base material.

7. The electrical connector of claim 1, wherein at least about 60% by volume of the plating material separates from the base material.

8. An electrical connector, comprising:

a housing;

a plurality of solder masses extending from a surface of the housing for electrically connecting the electrical connector to a circuit substrate; and

a retentive structure extending from the surface of the housing and spaced apart from the plurality of solder masses, the retentive structure made with a material that enables continued affixation of the electrical connector to a circuit substrate at temperatures sufficient to initiate reflow of the plurality of solder masses.

9. An electrical connector, comprising:

a housing;

a retentive structure extending from a surface of the housing for effecting a non-electrical connection with a circuit substrate, the retentive structure made with a material that alters a physical property of a solder composition in contact with the retentive structure at a reflow temperature of such a solder composition.

10. The electrical connector of claim 9, wherein the physical property is a melting temperature.

11. The electrical connector of claim 10, wherein the melting temperature is increased by at least about 10 degrees Celsius.

12. The electrical connector of claim 9, wherein the retentive structure is made with a base material and a plating material disposed over at least a portion of the base material.

13. The electrical connector of claim 12, wherein the plating material is selected from the group comprising gold, palladium, platinum, silver, rhodium, iridium, osmium, ruthenium, and rhenium.

14. The electrical connector of claim 9, wherein the plating material includes gold.

15. The electrical connector of claim 9, wherein the plating material includes palladium.

16. The electrical connector of claim 9, further comprising a plurality of solder masses extending from the surface of the housing for effecting an electrical connection with a circuit substrate.

17. An electrical connector, comprising:

a housing:

solder masses extending from a surface of the housing for electrically connecting the electrical connector to a circuit substrate; and

a retentive structure extending from the surface of the housing and spaced apart from the solder masses, the retentive structure comprising a material such that after initial affixation of the solder masses and retentive structure with a circuit substrate, affixation at the solder masses is compromised, due to an elevated temperature, prior to affixation at the retentive structure

18. An electronic assembly comprising:

a printed circuit substrate including a retentive through hole and a plurality of lands;

an electrical connector according to claim 1 engaged with the printed circuit substrate such that individual solder masses are affixed to individual lands and the retentive structure is affixed within the retentive through hole with a solder composition.

19. The electronic assembly of claim 18, further comprising a second electrical connector affixed to an opposite side of the printed circuit substrate than the electrical connector.